Materials Declaration Form

IPC	**1752**	**Version**	**2**
Form Type *	Distribute		
Sectionals *	Material Info Manufacturing Info	**Subsectionals ***	A-D
			**** : Required Field***

Supplier Information			
Company Name *	STMicroelectronics	**Response Date ***	15-08-2023
Company Unique ID	NL 008751171B01		
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact Phone *	Refer to Supplier Comment section	**Contact Email ***	Refer to Supplier Comment section
Authorized Representative *	Material Declaration champion	**Representative Title**	Material Declaration champion
Representative Phone *	Refer to Supplier Comment section	**Representative Email ***	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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Legal Statement

Supplier Acceptance *	true	**Legal Declaration ***	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as omprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Signature Not Verified

Digitally signed by MDF Champion
Date: 2023.08.15 15:07:17 +08:00

Product				
Mfr Item Number	**Mfr Item Name**	**Version**	**Mfr Site**	**Date**
STM32H573AII3Q	23OQ*484XXXX	A	9991	15-08-2023
	Amount	UoM	**Unit type**	**ST ECOPACK Grade**
	64.68	mg	Each	ECOPACK® 2
.	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)		

Manufacturing information				
J-STD-020 MSL Rating	**Classification Temp**	**Nbr of Reflow Cycles**		
3	260	3		
bulk Solder Termination	**Terminal Plating**	**Terminal Base Alloy**	**Comment**	
Not Applicable ; if coating is used or other bulk termaination : add in comments	NAC	Copper Alloy	**96.5Sn/3.5Ag**	

Package Designator	**Size**	**Nbr of instances**	**Shape**	
BGA	7x7	169	bulk solder	
Comment	Package : A0YV UFBGA 7X7X0.6 169L P 0.5 MM 8502430			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	**Response**
1 - Product(s) meets EU RoHS requirement without any exemptions	**TRUE**
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE

Exemption Id.	**Description**

QueryList : REACH-10 Jun 2022	
Query	**Response**
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH	**true**

CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						**Mfr Item Name**	**23OQ*484XXXX**				5999999.0	999999.1
Homogeneous Material	**Material Group**	**Mass**	**UoM**	**Level**	**Substance Category**	**Substance**	**CAS**	**Exempt**	**Mass**	**UoM**	**Concentration in homogeneous material (ppm)**	**Concentration in product (ppm)**
Die or dies	M-011 Other inorganic materials	2.028	mg	supplier	die	Silicon (Si)	7440-21-3		1.657	mg	817061	25618
				supplier	metallization	Aluminium (Al)	7429-90-5		0.044	mg	21696	680
				supplier	metallization	Copper (Cu)	7440-50-8		0.138	mg	68047	2134
				supplier	metallization	Nickel (Ni)	7440-02-0		0.001	mg	493	15
				supplier	metallization	Tantalum (Ta)	7440-25-7		0.022	mg	10848	340
				supplier	metallization	Titanium (Ti)	7440-32-6		0.004	mg	1972	62
				supplier	metallization	Tungsten (W)	7440-33-7		0.001	mg	493	15
				supplier	Passivation	Silicon Oxide	7631-86-9		0.161	mg	79389	2489
Substrate (A296720)	M-011 Other inorganic materials	19.466	mg	supplier	BT-substrate	Thermosetting resin (Inorganic filler)	Proprietary		1.557	mg	80000	24076
				supplier	BT-substrate	Glass cloth	65997-17-3		6.229	mg	320000	96305
				supplier	BT-substrate	Copper foil	7440-50-8		7.008	mg	360000	108343
				supplier	Solder mask	3-methoxy-3-methylbutylacetate	103429-90-9		0.973	mg	50000	15048
				supplier	Solder mask	Morpholinederivative	Proprietary		0.195	mg	10000	3010
				supplier	Solder mask	Barium Sulfate	7727-43-7		2.336	mg	120000	36114
				supplier	Solder mask	Talc containing no as bestiform fibers	14807-96-6		0.097	mg	5000	1505
				supplier	Solder mask	Dipropylene glycol monomethyl ether	34590-94-8		1.071	mg	55000	16552
DAF (ATB-125-12)	M-011 Other inorganic materials	2.965	mg	supplier	film	Butadiene, acrylonitrile polymer, carboxy-termi	68610-41-3		2.035	mg	686250	31458
				supplier	film	Formaldehyde, polymer with (chloromethyl)ox	37382-79-9		0.871	mg	293750	13466
				supplier	film	[3-(2,3-Epoxypropoxy)propyl]trimethoxysilane	2530-83-8		0.030	mg	10000	458
				supplier	film	Reaction product: bisphenol-A-(epichlorhydrin)	25068-38-6		0.030	mg	10000	458
Bonding wire (Cu)	Precious metals	1.972	mg	supplier	Bonding wire	Gold (Au)	7440-57-5		0.006	mg	3000	91
				supplier	Bonding wire	Copper (Cu)	7440-50-8		1.927	mg	977000	29787
				supplier	Bonding wire	Palladium (Pd)	7440-05-3		0.039	mg	20000	610
Encapsulation (KE-G1250AAS)	M-011 Other inorganic materials	34.140	mg	supplier	Molding Compound	Epoxy resin	Proprietary		1.366	mg	40000	21113
				supplier	Molding Compound	Silica(Fused)	60676-86-0,7631-86-9		30.726	mg	900000	475039
				supplier	Molding Compound	Phenol resin	Proprietary		1.912	mg	56000	29558
				supplier	Molding Compound	Carbon Black	1333-86-4		0.137	mg	4000	2111
Solderballs (96.5Sn/3.5Ag)	Solder	4.110	mg	supplier	Solder	Tin (Sn)	7440-31-5		3.966	mg	965000	61319
				supplier	Solder	Silver (Ag)	7440-22-4		0.144	mg	35000	2224